TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

Notification# 20190327002.0
Datasheet for SN74LVC2G157
Information Only

Date: April 02, 2019
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC2G157DCUR	null
SN74LVC2G157DCTR	null
SN74LVC2G157DCUT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190327002.0	**PCN Date:**	April 2, 2019
Title:	Datasheet for SN74LVC2G157		
Customer Contact:	PCN Manager	**Dept:**	Quality Services

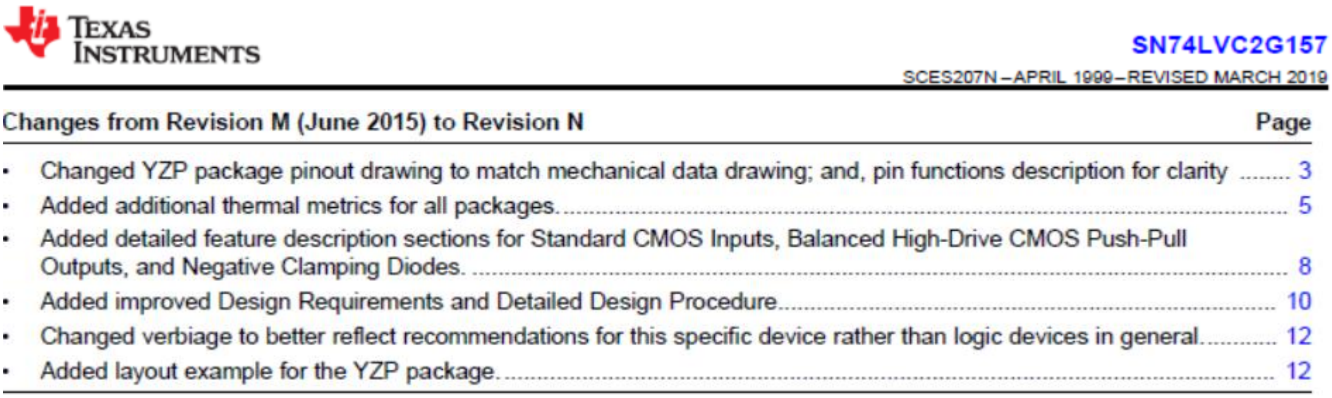
Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.



SN74LVC2G157

SCES207N – APRIL 1999 – REVISED MARCH 2019

Changes from Revision M (June 2015) to Revision N	Page
• Changed YZP package pinout drawing to match mechanical data drawing; and, pin functions description for clarity	3
• Added additional thermal metrics for all packages	5
• Added detailed feature description sections for Standard CMOS Inputs, Balanced High-Drive CMOS Push-Pull Outputs, and Negative Clamping Diodes	8
• Added improved Design Requirements and Detailed Design Procedure	10
• Changed verbiage to better reflect recommendations for this specific device rather than logic devices in general	12
• Added layout example for the YZP package	12

The datasheet number will be changing.

Device Family	Change From:	Change To:
SN74LVC2G157	SCES207M	SCES207N

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/SN74LVC2G157

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

74LVC2G157DCTRE4	74LVC2G157DCURG4	74LVC2G157DCUTG4	SN74LVC2G157DCT3
SN74LVC2G157DCTR	SN74LVC2G157DCTRG4	SN74LVC2G157DCU3	SN74LVC2G157DCUR
SN74LVC2G157DCUT	SN74LVC2G157YZPR		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com